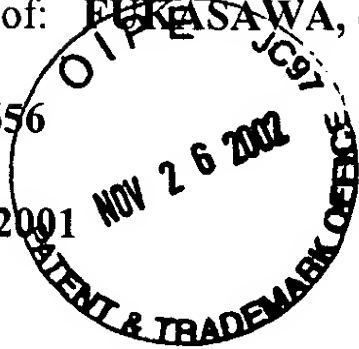


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **HIKASAWA, et al.**

Serial No.: 09/766,656

Filed: January 23, 2001



Group Art Unit: 2814

Prior Examiner: D. Graybill

P.T.O. Confirmation No.: 1144

**FOR: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE**

**AMENDMENT TRANSMITTAL**

Commissioner for Patents  
Washington, D.C. 20231

November 26, 2002

Sir:

Transmitted herewith is an Amendment in the above-identified application.  
The fee has been calculated as shown below:

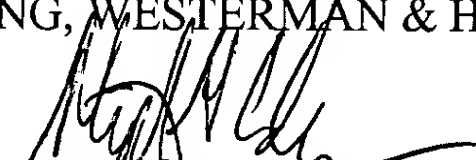
	CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional Fee
Total Claims	23	20	=	3	X \$9	X \$18	54.00
Independent Claims	6	8	=	0	X \$42	X \$84	0
First Presentation of Multiple Dependent Claims					\$140	280	
TOTAL FEES ENCLOSED:							\$54.00

**XX** Enclosed please find our check in the amount of \$54.00 for the additional claims fee in connection with this amendment.

**XX** The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. 01-2340. Two duplicates of this sheet are attached.

Respectfully submitted,

ARMSTRONG, WESTERMAN & HATTORI, LLP

  
Stephen G. Adrian  
Attorney for Applicants  
Reg. No. 32,878

SGA/arf

Atty. Docket No. **980233B**  
Suite 1000, 1725 K Street, N.W.  
Washington, D.C. 20006  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **FUKASAWA, et al.**

Group Art Unit: 2814

#8C J. Bruns  
J. Bruns  
1/29/03

Serial No.: 09/766,656

Prior Examiner: D. Graybill

Filed: January 23, 2001

P.T.O. Confirmation No.: 1144

For. **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE**

**SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Date: November 26, 2002

Sir:

Further to the Supplemental Preliminary Amendment filed February 21, 2002, please amend  
the above-captioned patent application as follows:

**IN THE CLAIMS:**

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**Please add new claims 111-120 as follows:**

111. A method for fabricating a semiconductor device comprising:

a resin sealing step of loading a wiring board having a flexible member on which a  
semiconductor element and leads are arranged onto a mold and supplying sealing resin to the  
semiconductor element so as to seal the semiconductor element; and

a protruding electrode forming step of forming protruding electrodes so as to be